MA2YD21

Silicon epitaxial planar type

For high frequency rectification

■ Features

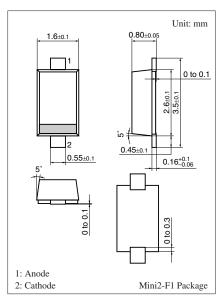
- Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible
- Low forward voltage: $V_F < 0.4 \text{ V}$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	15	V
Repetitive peak reverse voltage	V _{RRM}	15	V
Forward current (Average) *1	I _{F(AV)}	1.0	A
Non-repetitive peak forward surge current *2	I _{FSM}	3	A
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note) *1: Mounted on an alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

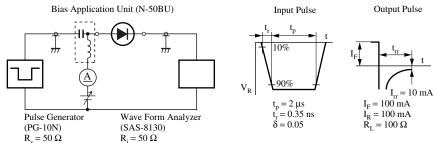


Marking Symbol: 2X

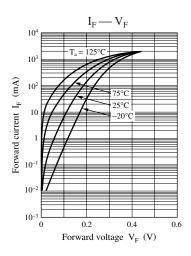
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

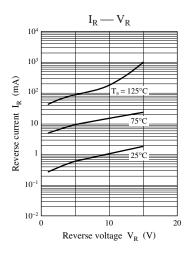
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 1 A$			0.4	V
Reverse current	I_R	$V_R = 6 \text{ V}$			1.5	mA
Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$		180		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		12		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

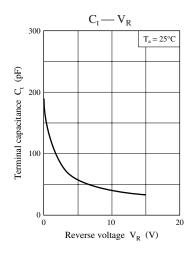
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. *: t_{rr} measurement circuit



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